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SUBSTRATE ASSEMBLING METHOD AND ASSEMBLING APPARATUS

ABSTRACT OF THE DISCLOSURE:

With conventional assembling apparatus, it has been difficult in a vacuum to laminate two substrates properly at the required clearance and within a short time when the
5 substrates are large in area. A new assembling apparatus has therefore been realized that ensures an almost uniform substrate-to-substrate clearance by providing pressurizing mechanisms for applying pressure to the
10 vicinity of the four corners of one rectangular substrate when two substrates are to be assembled by mechanical application of pressure, then monitoring the clearance between the substrates after the required pressure has been applied, and adjusting the pressurizing force of each
15 pressurizing mechanism according to monitoring results.

Figure 1

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